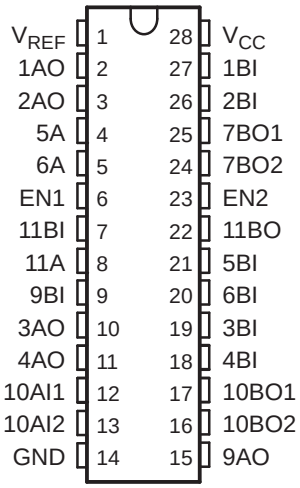
FEATURES

- **Operates as a GTL–/GTL/GTL+ to LVTTL or LVTTL to GTL–/GTL/GTL+ Translator**
- **Series Termination on TTL Output of 30 Ω**
- **Latch-Up Testing Done to JEDEC Standard JESD 78**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B, Class II)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

PW PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The SN74GTL2107 is a 12-bit translator that interfaces between the 3.3-V LVTTL chip set I/O and the Xeon™ processor GTL–/GTL/GTL+ I/O. The device is designed for platform health management in dual-processor applications.

PIN DESCRIPTION

PIN NO.	SYMBOL	NAME AND FUNCTION
1	V_{REF}	GTL reference voltage
2–6, 8, 10–13, 15, 23	ENn nAn	Data and enable inputs/outputs (LVTTL) on all inputs and pin 15 output. Remaining outputs are open drain.
7, 9, 16, 17–22, 24–27	nBn	Data inputs/outputs (GTL–/GTL/GTL+)
14	GND	Ground (0 V)
28	V_{CC}	Positive supply voltage

ORDERING INFORMATION

T_A	PACKAGE(1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – PW	Tube	SN74GTL2107PW	GK2107
		Tape and reel	SN74GTL2107PWR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLES(1)

INPUTS		OUTPUT 1AO/2AO (OPEN DRAIN)
EN1	1BI/2BI	
H	L	L
H	H	H
L	X	H

(1) H = High voltage level, L = Low voltage level

INPUTS		OUTPUT 3AO/4AO (OPEN DRAIN)
EN2	3BI/4BI	
H	L	L
H	H	H
L	X	H

INPUT 9BI	OUTPUT 9AO
L	L
H	H

INPUTS		OUTPUT 10BO1/10BO2
10AI1/10AI2	9BI	
L	L	L
L	H	L
H	L	L
H	H	H

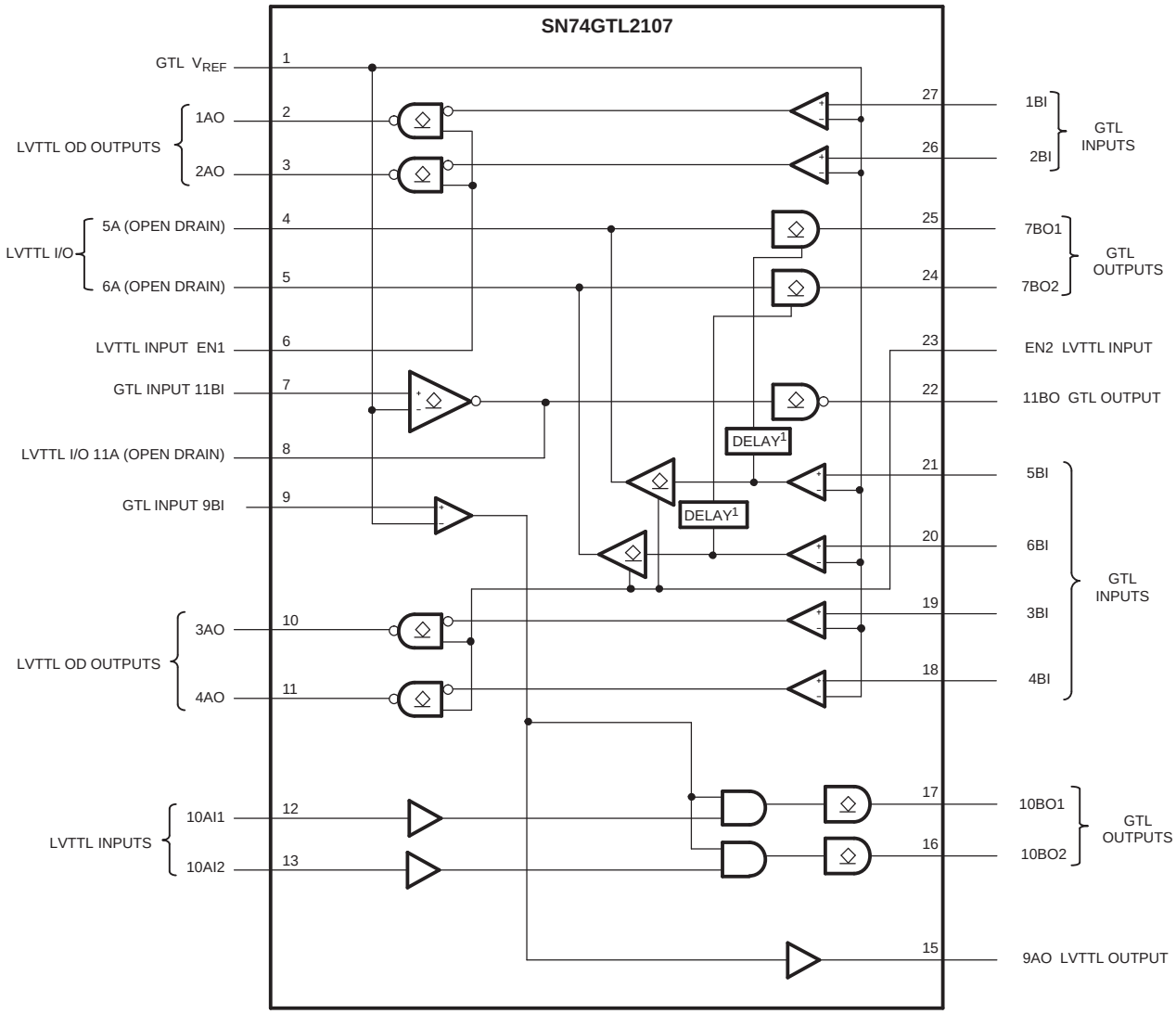
INPUTS		INPUT/OUTPUT 5A/6A (OPEN DRAIN)	OUTPUT 7BO1/7BO2
EN2	5BI/6BI		
H	L	L	H(1)
H	H	L(2)	L
H	H	H	H
L	H	L(2)	L
L	H	H	H
L	L	H	H
L	L	L(2)	H

(1) The enable on 7BO1/7BO2 includes a delay that prevents a transient condition (where 5BI/6BI goes from low to high, and the low to high on 5A/6A lags up to 100 ns) from causing a low glitch on the 7BO1/7BO2 outputs.
(2) Open-drain input/output terminal is driven to a logic-low state by an external driver.

INPUT 11BI	INPUT/OUTPUT 11A (OPEN DRAIN)	OUTPUT 11BO
L	H	L
L	L(1)	H
H	L	H

(1) Open-drain input/output terminal is driven to a logic-low state by an external driver.

LOGIC SYMBOL



(1) The enable on 7BO1/7BO2 includes a delay that prevents a transient condition (where 5BI/6BI go from low to high, and the low to high on 5A/6A lags up to 100 ns) from causing a low glitch on the 7BO1/7BO2 outputs.

Absolute Maximum Ratings(1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	4.6	V
V_I	Input voltage range(3)	A port (LVTTL)	–0.5	4.6	V
		B port (GTL)	–0.5	4.6	
V_O	Output voltage range (output in OFF or HIGH state)(3)	A port	–0.5	4.6	V
		B port	–0.5	4.6	
I_{IK}	Input diode current	$V_I < 0$		–50	mA
I_{OK}	Output diode current	$V_O < 0$		–50	mA
	Current into any output in the LOW state	A port		32	mA
		B port		30	
	Current into any output in the HIGH state	A port		–32	mA
θ_{JA}	Package thermal impedance(4)			62	°C/W
T_{stg}	Storage temperature range		–60	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) Voltages are referenced to GND (ground = 0 V).
(3) The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
(4) The performance capability of a high-performance integrated circuit, in conjunction with its thermal environment, can create junction temperatures that are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	3.3	3.6	V
V_{TT}	Termination voltage	GTL–	0.85	0.9	0.95	V
		GTL	1.14	1.2	1.26	
		GTL+	1.35	1.5	1.65	
V_{REF}	Reference voltage	Overall	0.5	2/3 V_{TT}	1.8	V
		GTL–	0.5	0.6	0.63	
		GTL	0.76	0.8	0.84	
		GTL+	0.87	1	1.1	
V_I	Input voltage	A port	0	3.3	3.6	V
		B port	0	V_{TT}	3.6	
V_{IH}	High-level input voltage	A port	2			V
		B port	V_{REF} + 50 mV			
V_{IL}	Low-level input voltage	A port			0.8	V
		B port			V_{REF} – 50 mV	
I_{OH}	High-level output current	A port			–16	mA
I_{OL}	Low-level output current	A port			16	mA
		B port			15	
T_A	Operating free-air temperature		–40		85	°C

Electrical Characteristics

over recommended operating conditions

PARAMETER		TEST CONDITIONS	–40°C to 85°C			UNIT
			MIN	TYP(1)	MAX	
V_{OH}(2)	A port	V_{CC} = 3 V to 3.6 V, I_{OH} = –100 µA	V_{CC} – 0.2			V
		V_{CC} = 3 V, I_{OH} = –16 mA	2.1			
V_{OL}(2)	A port	V_{CC} = 3 V, I_{OL} = 16 mA			0.8	V
	B port	V_{CC} = 3 V, I_{OL} = 15 mA			0.4	
I_I	A port	V_{CC} = 3.6 V, V_I = V_{CC}			±1	µA
		V_{CC} = 3.6, V_I = 0 V			±1	
	B port	V_{CC} = 3.6 V, V_I = V_{TT} or GND			±1	
I_{CC}	A or B port	V_{CC} = 3.6 V, V_I = V_{CC} or GND, I_O = 0			12	mA
ΔI_{CC}(3)	A port or control inputs	V_{CC} = 3.6 V, V_I = V_{CC} – 0.6 V			500	µA
C_{IO}	A port	V_O = 3 V or 0		5		pF
	B port	V_O = V_{TT} or 0		4		

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) This is the increase in supply current for each input that is at the specified LVTTL voltage, rather than V_{CC} or GND.

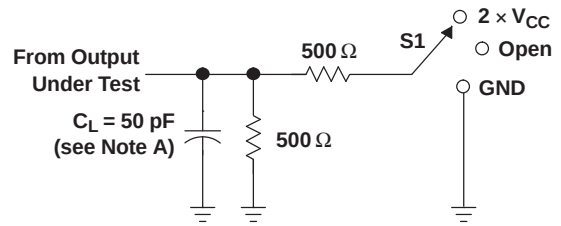
Switching Characteristics

over recommended operating free-air temperature range

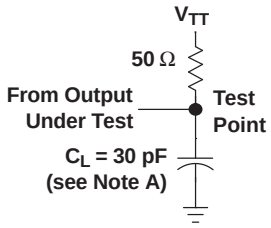
PARAMETER		WAVEFORM	GTL– V_{CC} = 3.3 V ± 0.3 V, V_{REF} = 0.6 V			GTL V_{CC} = 3.3 V ± 0.3 V, V_{REF} = 0.8 V			GTL+ V_{CC} = 3.3 V ± 0.3 V, V_{REF} = 1 V			UNIT
			MIN	TYP(1)	MAX	MIN	TYP(1)	MAX	MIN	TYP(1)	MAX	
t_{PLH}	An to Bn	1	2	4	8	2	4	8	2	4	8	ns
t_{PHL}			2	5.5	10	2	5.5	10	2	5.5	10	
t_{PLH}	9BI to 9AO	2	2	5.5	10	2	5.5	10	2	5.5	10	ns
t_{PHL}			2	5.5	10	2	5.5	10	2	5.5	10	
t_{PLH}	9BI to 10BOn	3	2	6	11	2	6	11	2	6	11	ns
t_{PHL}			2	6	11	2	6	11	2	6	11	
t_{PLH}	11BI to 11BO	3	2	8	13	2	8	13	2	8	13	ns
t_{PHL}(2)			2	14	21	2	14	21	2	14	21	
t_{PLH}	Bn to Bn	3	4	7	11	4	7	11	4	7	11	ns
t_{PHL}			120	205	350	120	205	350	120	205	350	
t_{PLZ}	ENn to An	5	1	3	7	1	3	7	1	3	7	ns
t_{PZL}			1	3	7	1	3	7	1	3	7	
t_{PLZ}	Bn to An (I/O)	4	2	5	10	2	5	10	2	5	10	ns
t_{PZL}			2	5	10	2	5	10	2	5	10	
t_{PLZ}	Bn to An	4	2	5	10	2	5	10	2	5	10	ns
t_{PZL}			2	5	10	2	5	10	2	5	10	
t_{PLZ}	EN2 to An (I/O)	5	1	3	7	1	3	7	1	3	7	ns
t_{PZL}			1	3	7	1	3	7	1	3	7	

(1) All typical values are measured at V_{CC} = 3.3 V and T_A = 25°C.
(2) Includes –7.6-ns RC rise time of test-load pullup on 11 A, 1.5-kΩ pullup, and 21-pF load on 11 A has approximately 23-ns RC rise time.

PARAMETER MEASUREMENT INFORMATION
V_{TT} = 1.2 V, V_{REF} = 0.8 V for GTL and V_{TT} = 1.5 V, V_{REF} = 1 V for GTL+

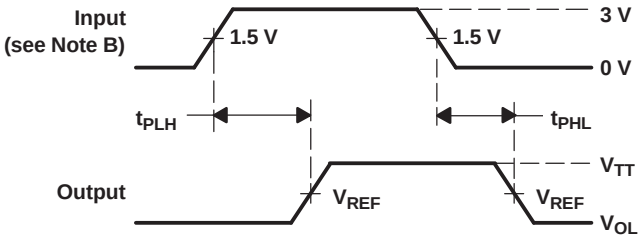


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}

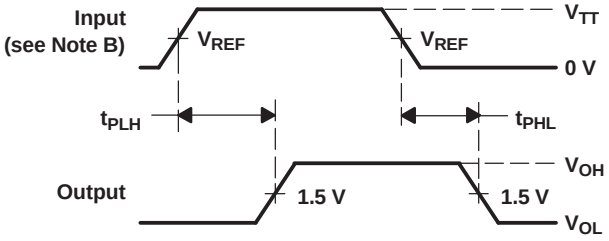


LOAD CIRCUIT FOR A OUTPUTS

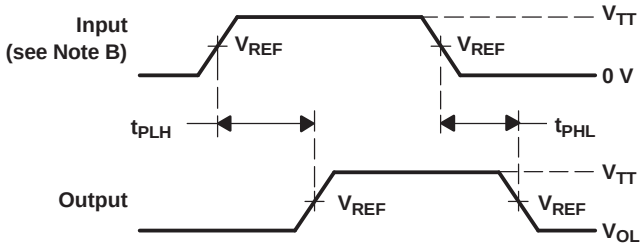
LOAD CIRCUIT FOR B OUTPUTS



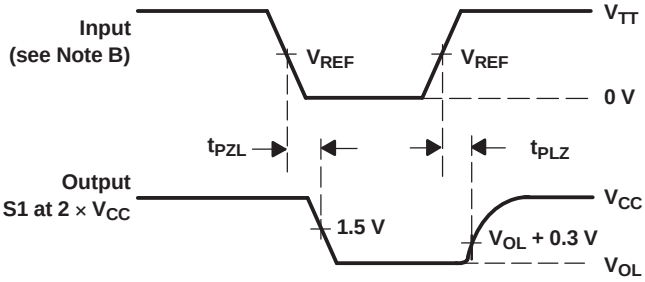
VOLTAGE WAVEFORM 1
PROPAGATION DELAY TIMES
(A port to B port)†



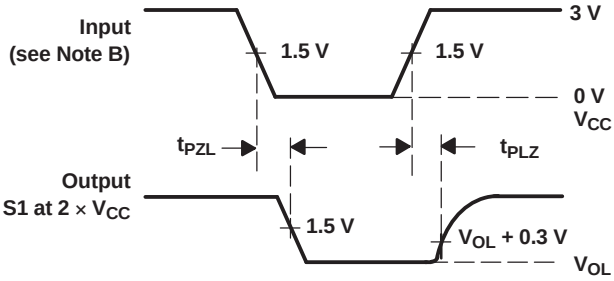
VOLTAGE WAVEFORM 2
PROPAGATION DELAY TIMES
(B port to A port)†



VOLTAGE WAVEFORM 3
PROPAGATION DELAY TIMES
(B port to B port)†



VOLTAGE WAVEFORM 4
PROPAGATION DELAY TIMES
(B port to A (I/O) port)†



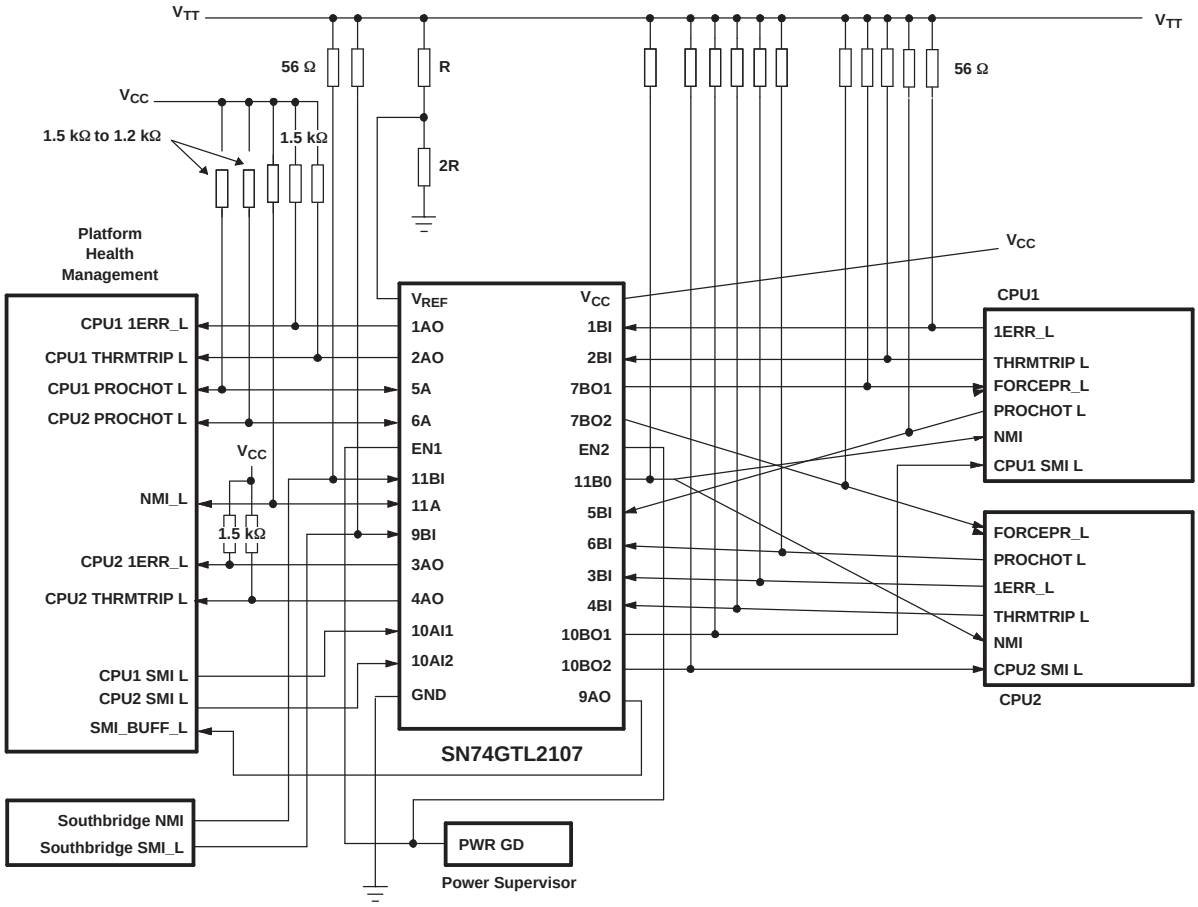
VOLTAGE WAVEFORM 5
ENABLE AND DISABLE TIMES
(EN2 to A(I/O) and ENn to An port)†

† All control inputs are LVTTL levels.

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

APPLICATION INFORMATION



Frequently Asked Questions

Question 1: On the SN74GTL2107 LVTTL input, specifically 10AI1 and 10AI2, when the SN74GTL2107 is powered down, these inputs may be pulled up to 3.3 V, and we want to ensure that there is no leakage path to the power rail under this condition. Are the LVTTL inputs high impedance when the device is powered down, and will there be any leakage?

Answer 1: When the device is powered down, the LVTTL inputs are in a high-impedance state and do not leak to V_{DD} if they are pulled high while the device is powered down.

Question 2: Do all the LVTTL inputs have the same powered-down characteristic?

Answer 2: Yes

Question 3: What is the condition of the other GTL I/O and LVTTL output pins when the device is powered down?

Answer 3: The open-drain outputs, both GTL and LVTTL, do not leak to the power supply if they are pulled high while the device is powered down. The GTL inputs also do not leak to the power supply under the same conditions. The LVTTL totem-pole outputs, however, are not open-drain type outputs, and there is current flow on these pins if they are pulled high when V_{DD} is at ground.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74GTL2107PW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	GK2107	Samples
SN74GTL2107PWG4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	GK2107	Samples
SN74GTL2107PWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	GK2107	Samples
SN74GTL2107PWRG4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	GK2107	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

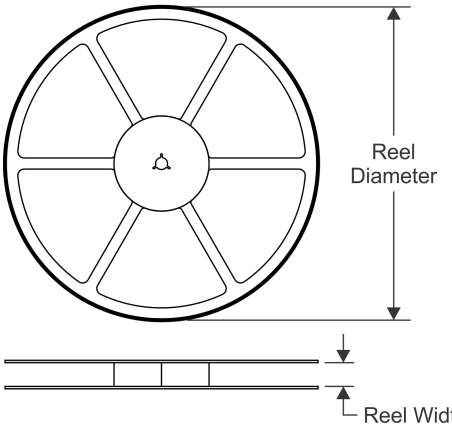
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

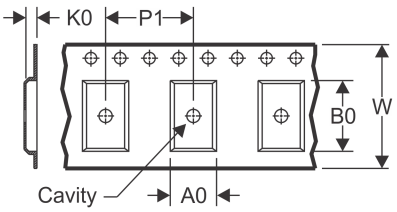
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

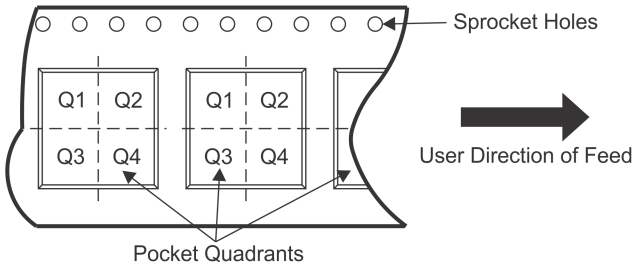


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

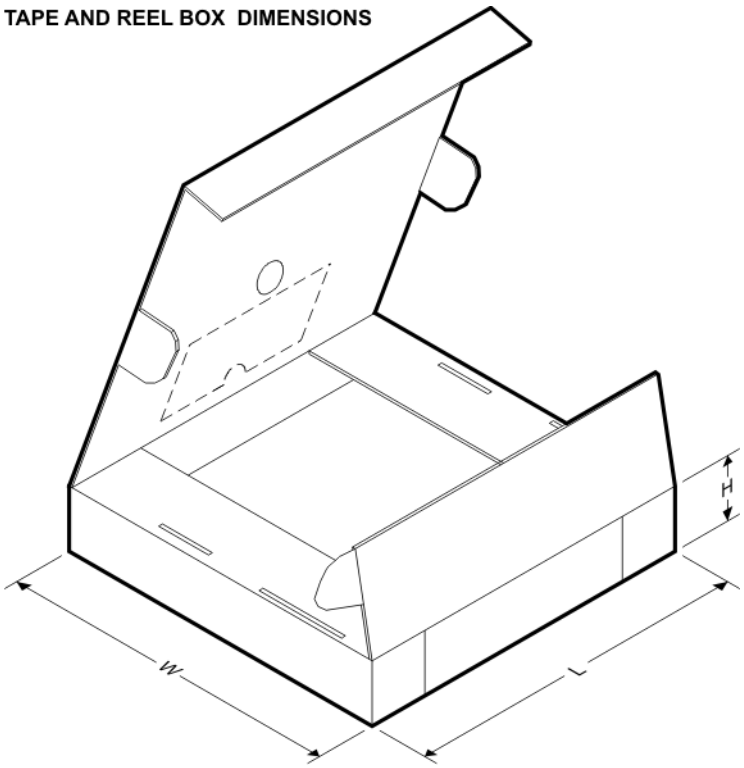
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74GTL2107PWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

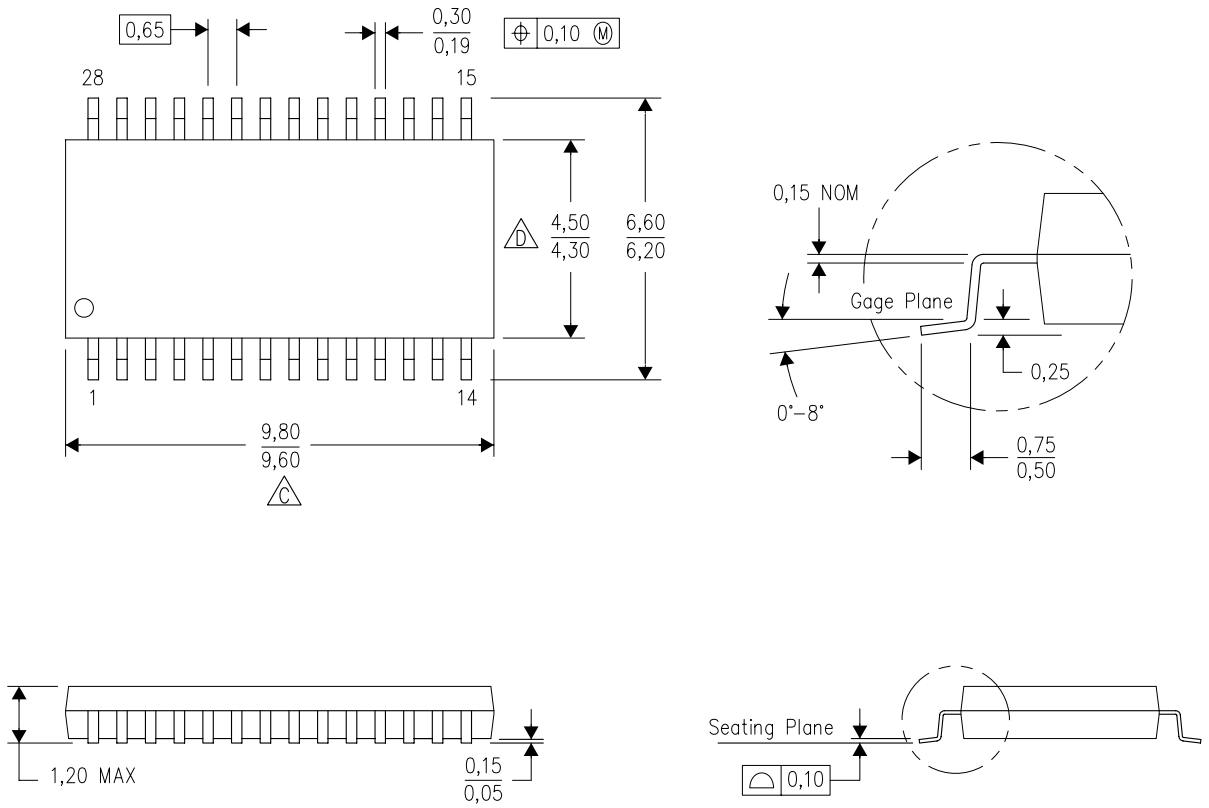
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74GTL2107PWR	TSSOP	PW	28	2000	367.0	367.0	38.0

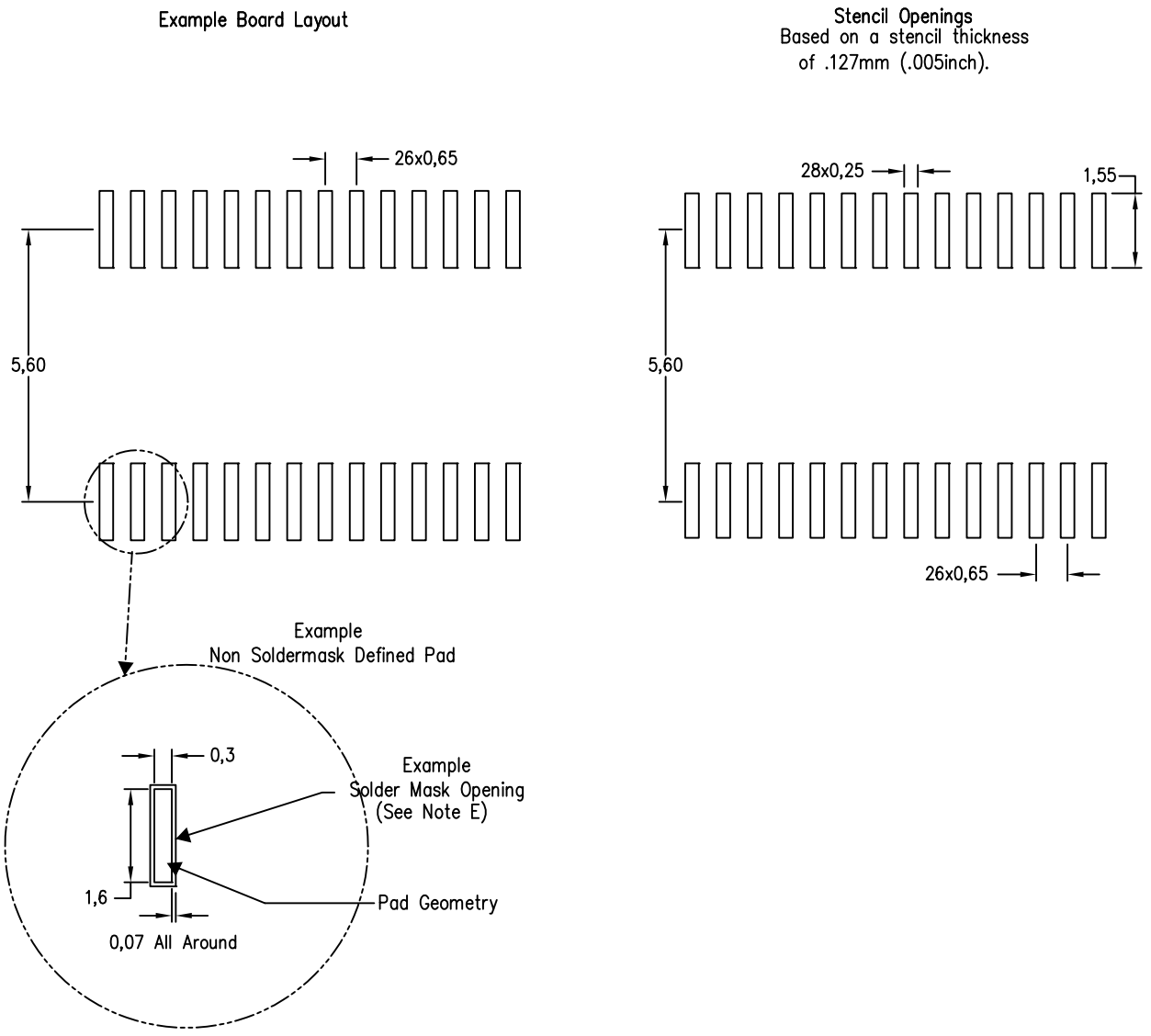
PW (R–PDSO–G28) PLASTIC SMALL OUTLINE



4040064–7/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G28) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265